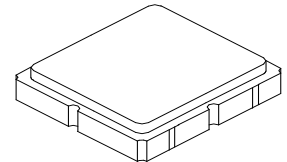


- **Low-loss SAW Filter**
- **No Matching Required for 50 ohm Source/Load**
- **3.8 x 3.8 x 1.4 mm Surface-mount Package**
- **Complies with Directive 2002/95/EC (RoHS)**



SF2276D-2

**453.75 MHz
SAW Filter**



SM3838-6

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Maximum DC Voltage on any Non-ground Terminals	5	VDC
Operable Temperature Range	-45 to +125	°C
Specification Temperature Range	-20 to +80	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260 °C for 30 s	

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_c			453.75		MHz
Insertion Loss, 450.0 to 457.5 MHz, -10 to +60 °C	IL			3.5	5.0	dB
Amplitude Ripple, 450.0 to 457.5 MHz, -10 to +60 °C				1.0	3.0	dB _{P-P}
Input Return Loss, 450.0 to 457.5 MHz			5	6		dB
Output Return Loss, 450.0 to 457.5 MHz			5	6		dB
Rejection Referenced to 0 dB:						dB
300 to 350 MHz			27	30		
350 to 445 MHz			25	28		
460 to 470 MHz, -10 to +60 °C			8	15		
470 to 2000 MHz			16	18		
Single-ended Source Impedance	50 ohm					
Single-ended Load Impedance	50 ohm					

Case Style	SM3838-6 3.8 x 3.8 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	A24, <u>YWWS</u>					
Standard Reel Quantity	Reel Size 7 Inch					500 Pieces/Reel
	Reel Size 13 Inch					3000 Pieces/Reel

Electrical Connections

Connection	Terminals
Port 1	2
Port 2	5
Case Ground	All others

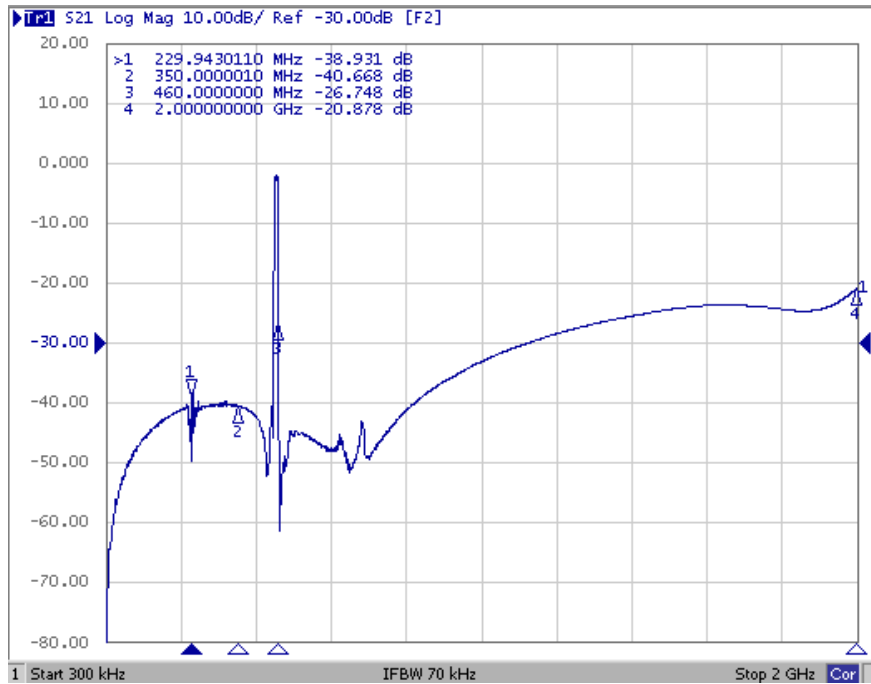
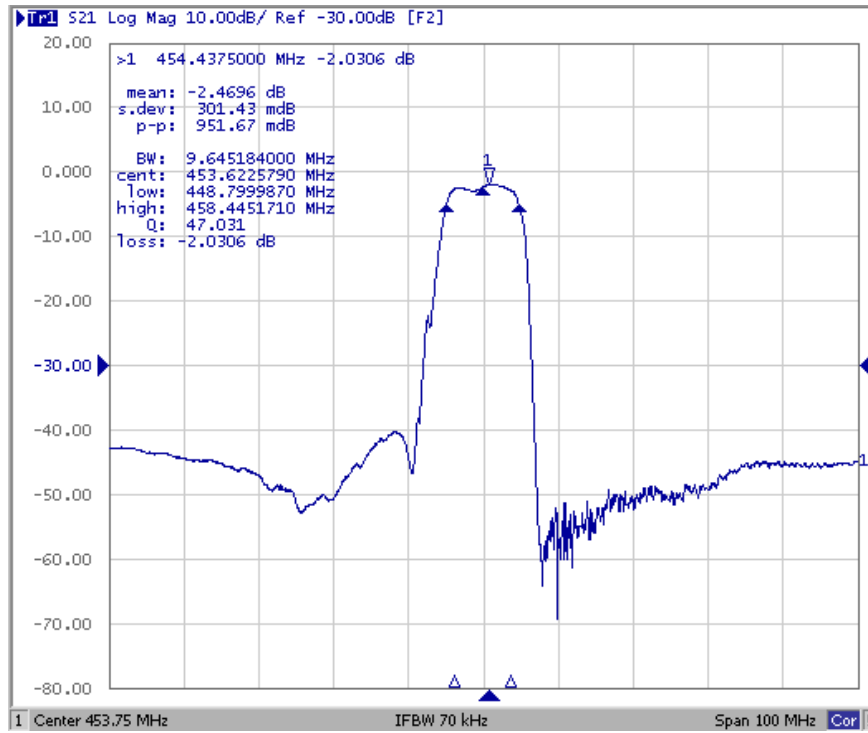


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

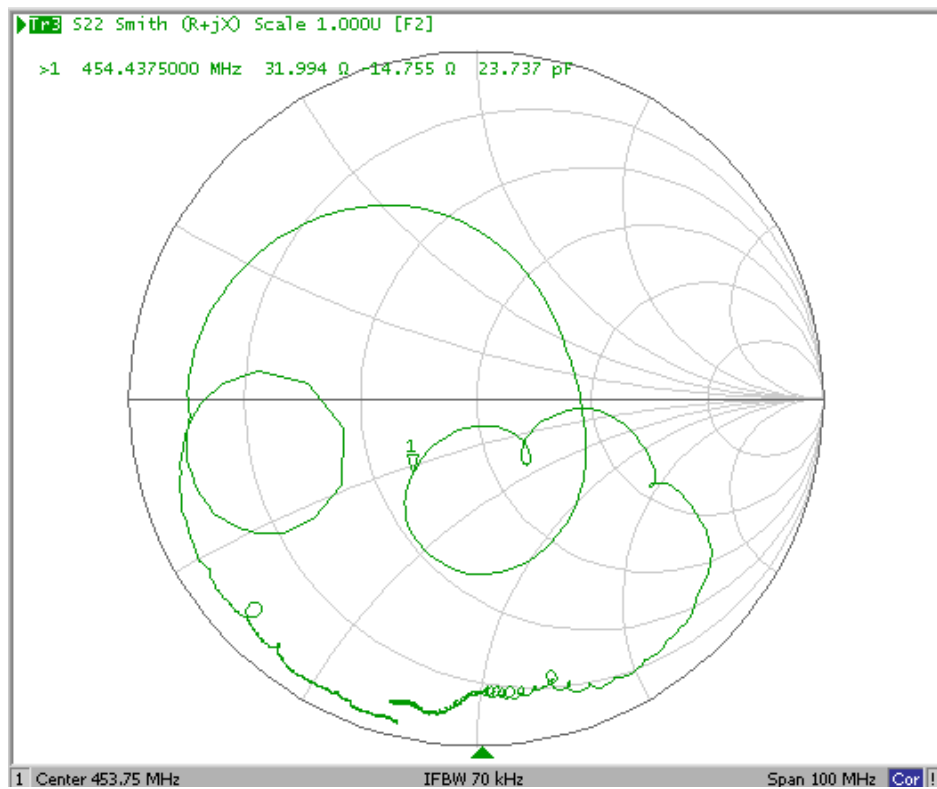
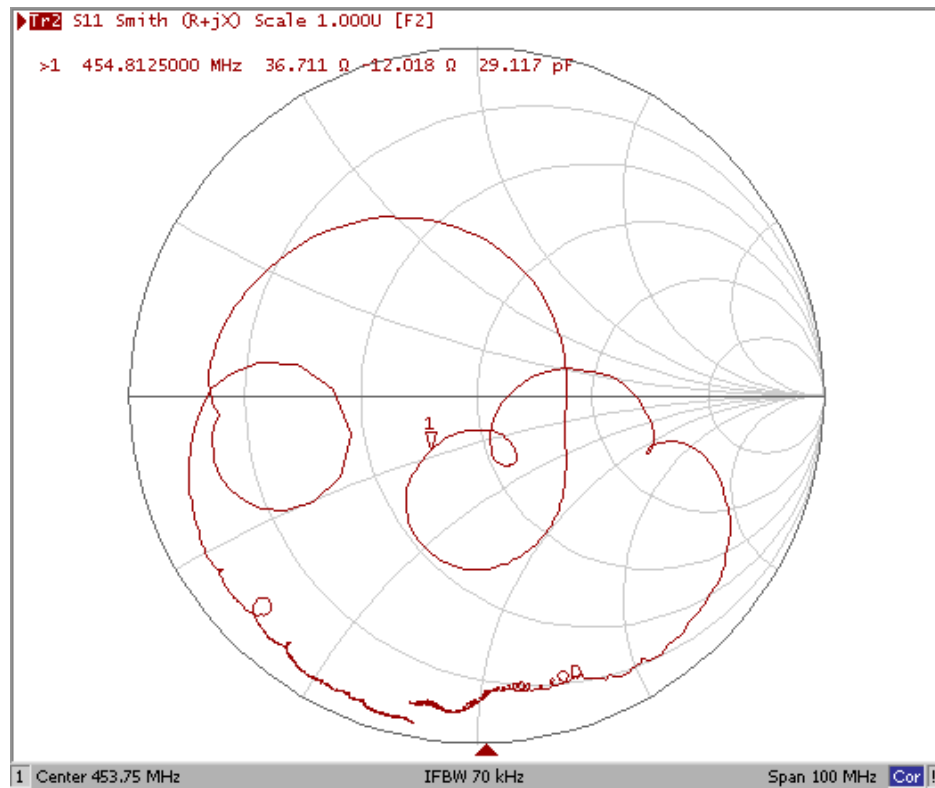
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.

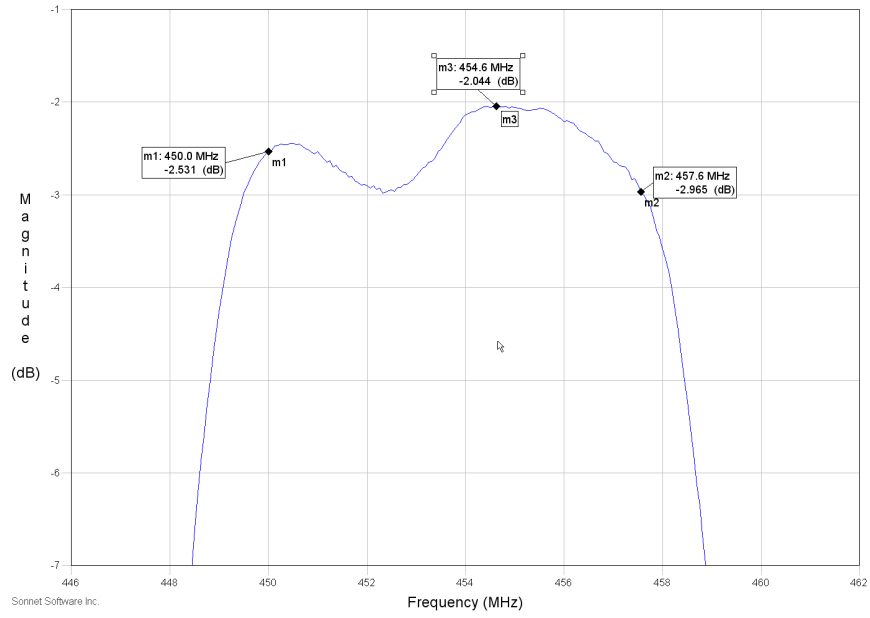
Filter Response Plots



Filter Input and Output Impedance Plots



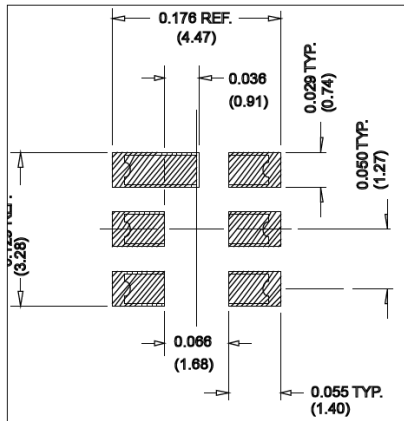
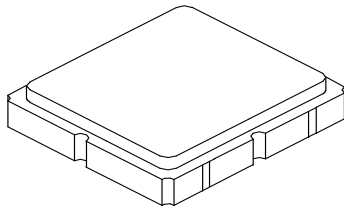
Filter Passband Detail



SM3838-6 Case

6-Terminal Ceramic Surface-mount Case

3.8 X 3.8 mm Nominal Footprint



Typical PCB Land Footprint

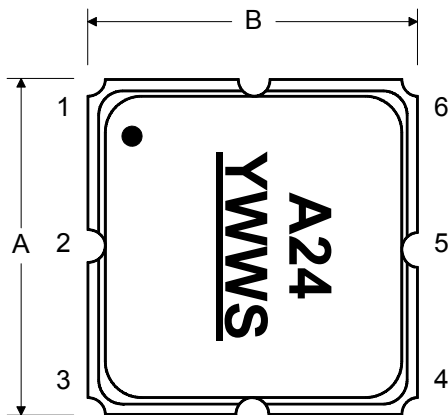
Case Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	3.60	3.80	4.00	0.140	0.150	0.016
B	3.60	3.80	4.00	0.140	0.150	0.016
C	1.07	1.25	1.43	0.050	0.060	0.067
D	0.95	1.10	1.25	0.037	0.043	0.050
E	2.39	2.54	2.69	0.090	0.100	0.110
G	0.90	1.00	1.10	0.035	0.040	0.043
H	1.90	2.00	2.10	0.750	0.080	0.830
I	0.50	0.60	0.70	0.020	0.024	0.028
J	1.70	1.80	1.90	0.067	0.070	0.075

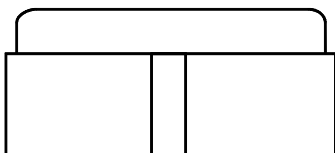
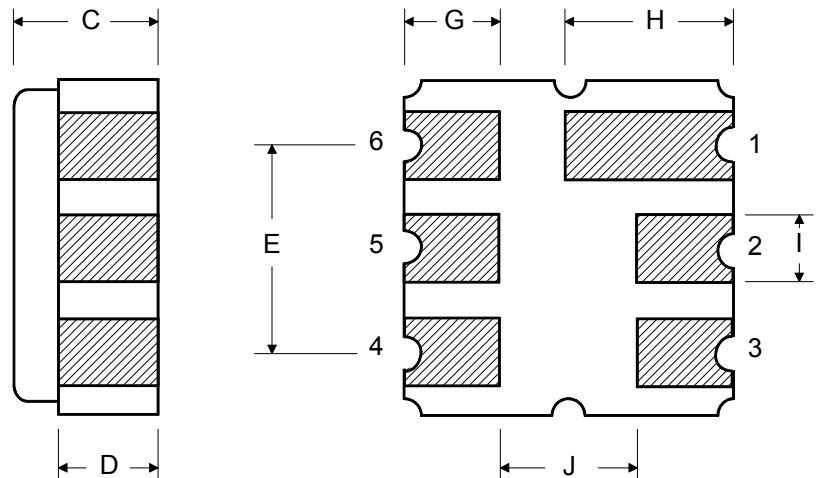
Materials

Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic
Pb Free	

TOP VIEW



BOTTOM VIEW



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

